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(54) Title: MOULD PART, MOULD AND METHOD FOR ENCAPSULATING ELECTRONIC COMPONENTS MOUNTED ON A CARRIER

(57) Abstract

The invention relates to a mould part of a mould for encapsulating electronic components mounted on a carrier, comprising at least one mould cavity provided in said mould part and at least one runner for moulding material connecting to said mould cavity, wherein the gate from said runner to said mould cavity has an oblong shape. The invention also relates to a mould with at least one such mould part. The invention also provides a method for encapsulating electronic components mounted on a carrier, wherein the liquid moulding material is fed into the mould cavity through a wide supply opening. Finally, the invention also provides an encapsulated electronic component mounted on a carrier, which component is manufactured by this method.

